ON Semiconductor

Is Now



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Unbuffered Inverter

The NL17SGU04 MiniGate[™] is an advanced high–speed CMOS unbuffered inverter in ultra–small footprint.

The NL17SGU04 input structures provides protection when voltages up to 3.6 V are applied.

Features

- Wide Operating V_{CC} Range: 0.9 V to 3.6 V
- High Speed: $t_{PD} = 1.9 \text{ ns}$ (Typ) at $V_{CC} = 3.0 \text{ V}$, $C_L = 15 \text{ pF}$
- Low Power Dissipation: $I_{CC} = 0.5 \mu A$ (Max) at $T_A = 25^{\circ}C$
- 3.6 V Overvoltage Tolerant (OVT) Input Pins
- Ultra-Small Packages
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

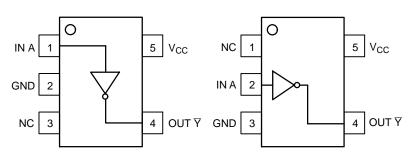


Figure 1. SOT-953 (Top Thru View)

Figure 2. SC-88A (Top View)

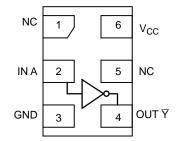


Figure 3. UDFN (Top View)



Figure 4. Logic Symbol



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SC-88A DF SUFFIX

CASE 419A



SOT-953 CASE 527AE





UDFN6 1.0 x 1.0 CASE 517BX





UDFN6 1.45 x 1.0 CASE 517AQ



M = Date Code*
■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

	PIN ASSIGNMENT							
	SOT-953 SC-88A UDFN6							
1	IN A	NC	NC					
2	GND	IN A	IN A					
3	NC	GND	GND					
4	OUT \(\overline{Y} \)	OUT \(\overline{Y} \)	OUT ₹					
5	V _{CC}	V _{CC}	NC					
6			V _{CC}					

FUNCTION TABLE

A Input	▼ Output
L	Н
Н	L

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet

MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +4.6	V
V _{IN}	DC Input Voltage		-0.5 to +4.6	V
V _{OUT}	DC Output Voltage	Output at High or Low State Power–Down Mode (V _{CC} = 0 V)	-0.5 to V _{CC} +0.5 -0.5 to +4.6	V
I _{IK}	DC Input Diode Current	V _{IN} < GND	-20	mA
I _{OK}	DC Output Diode Current	V _{OUT} < GND	-20	mA
I _{OUT}	DC Output Source/Sink Current		±20	mA
I _{CC}	DC Supply Current per Supply Pin		±20	mA
I _{GND}	DC Ground Current per Ground Pin		±20	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C	
TJ	Junction Temperature Under Bias		+150	°C
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3)	>2000 >150	V
I _{LATCHUP}	Latchup Performance Above V _{CC} ar	nd Below GND at 125°C (Note 4)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Measured with mainimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.

- Tested to EIA/JESD22-A114-A.
 Tested to EIA/JESD22-A115-A.
- 4. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	0.9	3.6	V
V_{IN}	Digital Input Voltage	0.0	3.6	V
V _{OUT}	Output Voltage Output at High or Low State Power–Down Mode ($V_{CC} = 0 \ V_{CC}$	e 0.0 ') 0.0	V _{CC} 3.6	V
T _A	Operating Temperature Range	-55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fail Rate $V_{CC} = 3.3 \text{ V} \pm 0.3$	V 0	10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

					T _A = 25°C		25°C				
Symbol	Parameter	C	onditions	V _{CC} (V)	Min	Max	Min	Max	Unit		
V_{IH}	High-Level Input			0.9	V _{CC}		V _{CC}		V		
	Voltage			1.1 to 1.3	0.7xV _{CC}		0.7xV _{CC}				
				1.4 to 1.6	0.65xV _{CC}		0.65xV _{CC}				
				1.65 to 1.95	0.65xV _{CC}		0.65xV _{CC}				
				2.3 to 2.7	1.7		1.7				
				3.0 to 3.6	2.0		2.0				
V_{IL}	Low-Level Input			0.9		GND		GND	V		
	Voltage			1.1 to 1.3		0.3xV _{CC}		0.3xV _{CC}			
				1.4 to 1.6		0.35xV _{CC}		0.35xV _{CC}			
				1.65 to 1.95		0.35xV _{CC}		0.35xV _{CC}			
				2.3 to 2.7		0.7		0.7			
				3.0 to 3.6		0.8		0.8			
V _{OH}	H High-Level Output Voltage		V _{IN} =	$I_{OH} = -20 \mu A$	0.9	0.75		0.75		V	
			Output Voltage	Output Voltage	V _{IH} or V _{IL}	I _{OH} = -0.3 mA	1.1 to 1.3	0.75xV _{CC}		0.75xV _{CC}	
			I _{OH} = -1.7 mA	1.4 to 1.6	0.75xV _{CC}		0.75xV _{CC}				
			I _{OH} = -3.0 mA	1.65 to 1.95	Vcc-0.45		Vcc-0.45				
			I _{OH} = -4.0 mA	2.3 to 2.7	2.0		2.0		1		
			I _{OH} = -8.0 mA	3.0 to 3.6	2.48		2.48				
V _{OL}	Low-Level	V _{IN} =	I _{OL} = 20 μA	0.9		0.1		0.1	V		
	Output Voltage	V _{IH} or V _{IL}	I _{OL} = 0.3 mA	1.1 to 1.3		0.25xV _{CC}		0.25xV _{CC}			
			I _{OL} = 1.7 mA	1.4 to 1.6		0.25xV _{CC}		0.25xV _{CC}			
			I _{OL} = 3.0 mA	1.65 to 1.95		0.45		0.45			
			I _{OL} = 4.0 mA	2.3 to 2.7		0.4		0.4			
			I _{OL} = 8.0 mA	3.0 to 3.6		0.4		0.4			
I _{IN}	Input Leakage Current	0 ≤	V _{IN} ≤ 3.6 V	0 to 3.6		±0.1		±1.0	μΑ		
I _{CC}	Quiescent Supply Current	V _{IN} =	V _{CC} or GND	3.6		0.5		10.0	μΑ		

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

AC ELECTRICAL CHARACTERISTICS Input $t_f = t_f = 3.0 \text{ ns}$

Symbol	Parameter	Test Condition	V _{CC} (V)		T _A = 25° (C		=) +125°C		
				Min	Тур	Max	Min	Max	Unit	
t _{PLH} ,	Propagation Delay,	C _L = 10 pF,	0.9	-	8.0	10.3	-	13.3	ns	
t _{PHL}	A to Y	$R_L = 1 M\Omega$	1.1 to 1.3	-	6.0	9.4	-	12.2		
			1.4 to 1.6	-	3.2	8.5	-	10.0		
			1.65 to 1.95	-	2.6	6.2	-	6.7		
			2.3 to 2.7	-	2.0	3.9	-	4.4		
			3.0 to 3.6	-	1.7	3.1	-	3.7		
		C _L = 15 pF,	0.9	-	19.5	11.7	-	14.5	ns	
		$R_L = 1 \text{ M}\Omega$	1.1 to 1.3	-	7.0	9.2	-	12.2	- - - -	
			1.4 to 1.6	-	3.5	6.3	-	10.2		
			1.65 to 1.95	-	3.0	5.9	-	7.1		
			2.3 to 2.7	-	2.3	4.4	-	5.0		
			3.0 to 3.6	-	1.9	3.4	-	3.9		
		C _L = 30 pF,	0.9	-	10.0	12.5	-	15.6	ns	
		$R_L = 1 M\Omega$	1.1 to 1.3	-	9.0	11.6	-	13.8		
				1.4 to 1.6	-	6.0	9.1	-	12.9	1
	1.65	1.65 to 1.95	-	4.5	8.2	-	9.6	1		
			2.3 to 2.7	-	3.2	5.7	-	6.1	1	
			3.0 to 3.6	-	2.5	4.4	-	4.8		
C _{IN}	Input Capacitance		0 to 3.6		3	-	-	-	pF	
C _O	Output Capacitance	V _O = GND	0		3	-	-	-	pF	
C _{PD}	Power Dissipation Capacitance (Note 5)	f = 10 MHz	0.9 to 3.6	-	4	-	-	-	pF	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

5. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC} \cdot C_{PD}$ is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

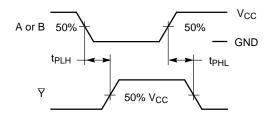
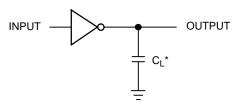


Figure 5. Switching Waveforms



*Includes all probe and jig capacitances A 1-MHz square input wave is recommended for propagation delay tests.

Figure 6. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NL17SGU04P5T5G	SOT-953 (Pb-Free)	8000 / Tape & Reel
NL17SGU04DFT2G	SC-88A (Pb-Free)	3000 / Tape & Reel
NLV17SGU04DFT2G*	SC-88A (Pb-Free)	3000 / Tape & Reel
NL17SGU04AMUTCG (In Development)	UDFN6 1.45x1 mm (Pb-Free)	3000 / Tape & Reel
NL17SGU04CMUTCG (In Development)	UDFN6 1x1 mm (Pb-Free)	3000 / Tape & Reel
NLV17SGU04AMUTCG* (In Development)	UDFN6 1.45x1 mm (Pb-Free)	3000 / Tape & Reel
NLV17SGU04CMUTCG* (In Development)	UDFN6 1x1 mm (Pb-Free)	3000 / Tape & Reel

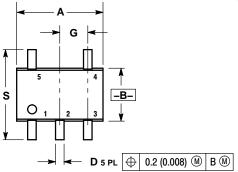
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

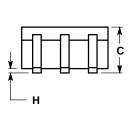
^{*}NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

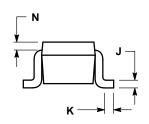
PACKAGE DIMENSIONS

SC-88A (SC-70-5/SOT-353) CASE 419A-02

ISSUE L



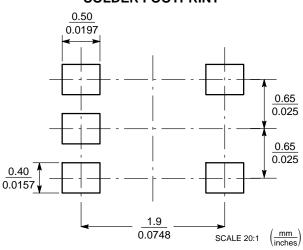




- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BLIEDS BURRS.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65 BSC	
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20	REF
S	0.079	0.087	2 00	2 20

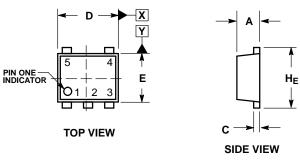
SOLDER FOOTPRINT*

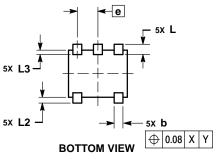


*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SOT-953 CASE 527AE **ISSUE E**





- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

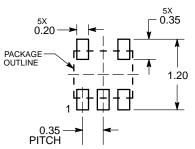
 2. CONTROLLING DIMENSION: MILLIMETERS

 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	0.34	0.37	0.40			
b	0.10	0.15	0.20			
С	0.07	0.12	0.17			
D	0.95	1.00	1.05			
E	0.75	0.80	0.85			
е		0.35 BS	С			
HE	0.95	1.00	1.05			
L	0.175 REF					
L2	0.05	0.10	0.15			
L3			0.15			

SOLDERING FOOTPRINT*

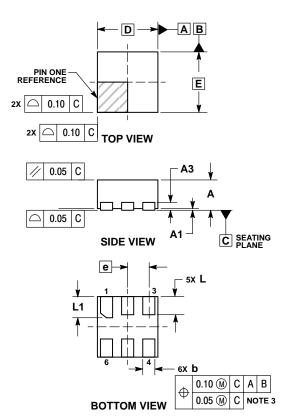


DIMENSIONS: MILLIMETERS

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

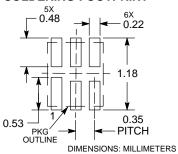
UDFN6 1.0x1.0, 0.35P CASE 517BX **ISSUE O**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
 4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

	MILLIMETERS				
DIM	MIN	MAX			
Α	0.45	0.55			
A1	0.00	0.05			
А3	0.13 REF				
b	0.12	0.22			
D	1.00 BSC				
E	1.00 BSC				
е	0.35 BSC				
L	0.25	0.35			
11	0.30	0.40			

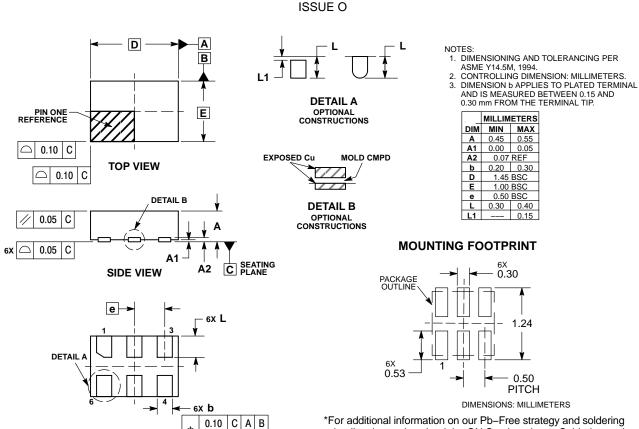
RECOMMENDED SOLDERING FOOTPRINT*



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PACKAGE DIMENSIONS

UDFN6 1.45x1.0, 0.5P CASE 517AQ ISSUE O



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BOTTOM VIEW

0.05

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